

REMARKS

In a final Office Action mailed July 3, 2006, claims 1 and 4-6 were examined. Claim 1 is amended. Claims 1 and 4-6 remain in the Application.

The Patent Office objects to the drawings and rejects claims 1 and 4-6 under 35 U.S.C. §103(a). Reconsideration of the pending claims is respectfully requested in view of the above amendment and the following remarks.

A. Objection to Drawings

The Patent Office objects to the drawings for failing to show “a plurality of interconnects disposed between the plurality of circuit substrates.” Applicant submits an amended Figure 6 with reference numbered 125 corresponding to an interconnect disposed between two circuit substrates. Applicant also amends paragraph [0028] of the Application to include reference number 125.

Applicant respectfully requests that the Patent Office accept amended Figure 6 and enter the amendment to paragraph [0028]. Applicant also respectfully requests that the Patent Office withdraw the objection to the drawings.

B. 35 U.S.C § 103(a): Rejection of Claims 1 & 4-6

The Patent Office rejects claims 1 and 4-6 under 35 U.S.C. § 103(a) as obvious over U.S. Patent Number 5,591,678 of Bendik, et al. (Bendik) in view of U.S. Patent Number 6,248,646 of Okojie (Okojie). According to the Patent Office Bendik discloses in **Figure 1** an apparatus comprising a plurality of circuit substrate in a non-planar orientation with a circuit substrate including a single semiconductor having a smallest dimension reduced with circuit devices formed in the single crystal layer. Okojie is cited for disclosing a plurality of circuit substrates on a substrate and in a non-planar orientation relative to one another and smallest dimension of a substrate comprising a thickness less than 100 microns.

Independent claim 1 is not obvious over the cited references because the cited references do not describe an apparatus including a plurality of circuit substrates on a substrate and the

plurality of circuit substrates are in a non-planar orientation stacked one on the other each circuit device consisting of a single crystal layer. With regard to the circuit substrate, the Patent Office relies on Bendik which shows multilayer circuit substrate, including, for example, wafer layer 46 and etch-stop layer 44. Thus, the circuit substrates in Bendik consist of more than a single crystal silicon layer.

For the above stated reason, independent claim 1 is not obvious over the cited references. Claims 4-6 depend from claim 1 and therefore contain all the limitations of that claim. For at least the reason stated with respect to claim 1, claims 4-6 are not obvious over the cited references.

Applicant respectfully requests the Patent Office withdraw the rejection to claims 1 and 4-6.

CONCLUSION

In view of the foregoing, it is believed that all claims now pending patentably define the subject invention over the prior art of record and are in condition for allowance and such action is earnestly solicited at the earliest possible date.

If necessary, the Commissioner is hereby authorized in this, concurrent and future replies, to charge payment or credit any overpayment to Deposit Account No. 02-2666 for any additional fees required under 37 C.F.R. §§ 1.16 or 1.17, particularly extension of time fees.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

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William T. Babbitt
William Thomas Babbitt, Reg. No. 39,591

12400 Wilshire Boulevard
Seventh Floor
Los Angeles, California 90025
Telephone (310) 207-3800
Facsimile (310) 820-5988

CERTIFICATE OF TRANSMISSION

I hereby certify that this correspondence is being submitted electronically via EFS Web on the date shown below to the United States Patent and Trademark Office.

Nedy Calderon
Nedy Calderon

9/29/06
Date